

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	585	watanabe near shinji.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:30
L2	9	tsunabuchi near masashi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:33
L3	3251	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:33
L4	177200	"438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:33
L5	383	((discrete or independent) near3 (substrate or wafer)) and (chip or die or dye or component) near5 (mount\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:56
L6	886	((discrete or independent) near3 (substrate or wafer)) and (chip or die or dye or component) near5 (mount\$3) and (method).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:36
L7	653	((discrete or independent) near3 (substrate or wafer)) and (chip or die or dye or component) near5 (mount\$3) and ((method) with (substrate or wafer)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:37
L8	358	((discrete or independent) near3 (substrate or wafer)) and (chip) near5 (mount\$3) and ((method) with (substrate or wafer)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:43
L9	3	((discrete or independent) near3 (substrate or wafer)) and (chip) near5 (mount\$3) and ((method) with ((supplying) near10 (substrate or wafer))).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:38

L10	7	((discrete or independent) near3 (substrate or wafer)) and (chip) near5 (mount\$3) and ((method) with ((supplying) near10 (substrate or wafer)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:38
L11	713	((discrete or independent) near3 (substrate or wafer)) and (chip) near5 (mount\$3) and ((method) with (substrate or wafer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:43
L12	713	11 and (chip) near15 (mount\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:44
L13	713	11 and (chip) near10 (mount\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:44
L14	486	13 and ((discrete) near3 (substrates or wafers))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:45
L15	134	13 and ((discrete) near (substrates or wafers))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:56
L16	1878	((discrete) near (substrates or wafers))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:56
L17	289025	(chip or die or dye or component) near5 (mount\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:56
L18	366	16 and 17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 10:57
L19	40	18 and ((discrete) near (substrates or wafers)) with (chip or die or dye or component) near5 (mount\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:07

L20	40	((discrete) near (substrates or wafers)) with (chip or die or dye or component) near5 (mount\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:07
L21	10	((discrete) near (substrates or wafers)) with (chip or die or dye or component) near5 (mounting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:07
L22	16	((discrete) near (substrates or wafers)) with (chip or die or dye or component or ic or integrated near circuit) near5 (mounting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:08
L23	55	((discrete) near (substrates or wafers)) near25 (mounting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:17
L24	33	((independent) near (substrates or wafers)) near25 (mounting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:13
L25	1324	((discrete or independent) near5 (substrates or wafers)) with (mount\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:22
L26	458	25 and (method with mount\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:22
L27	2261	((discrete or independent) near5 (substrates or wafers)) same (mount\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:22
L28	605	27 and (method near15 mount\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 11:22

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L1	374	(substrate or wafer) with (stage) with (conveyor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:35
L2	13	(substrate or wafer) with (stage) with (conveyor) same (chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:37
L3	77	(substrate or wafer) with (stage) with (convey\$3) same (chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:41
L4	2	(substrate or wafer) with (stage) with (convey\$3) same (remov\$3 near15 chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:37
L5	368184	(remov\$3) with (chip or die or dye or dice or component or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:42
L6	18110	(remov\$3) near15 (substrate or wafer) with (chip or die or dye or dice or component or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:43
L7	63	(remov\$3) near15 (substrate or wafer) with (chip or die or dye or dice or component or ic) and (convey\$3) with (stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:47
L8	4596	(remov\$3) near15 (substrate or wafer) with (chip or die or dye or dice or component or ic) and (stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:48
L9	2371	(remov\$3) near3 (substrate or wafer) with (chip or die or dye or dice or component or ic) and (stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:48

L10	2311	(remov\$3) near3 (substrate or wafer) near25 (chip or die or dye or dice or component or ic) and (stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:49
L11	1096	(remov\$3) near (substrate or wafer) near25 (chip or die or dye or dice or component or ic) and (stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:58
L12	135	11 and (substrate or wafer) near (carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:49
L13	26	11 and (method near15 supplying)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:58
L14	75094	(substrate or wafer) near25 (chip or die or dye or dice or component or ic) and (stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:20
L15	3704	14 and ((method) near15 (chip near15 substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 13:59
L16	712	14 and ((method) near15 (chip near15 substrate)) near15 (mounting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:20
L17	366762	(substrate or wafer) near25 (chip or die or dye or dice or component or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:20
L18	3164	17 and ((method) near15 (chip near15 substrate)) near15 (mounting)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:20
L19	15	18 and (convey\$3) near15 (stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/02 14:21